

- (57) Abstract:** A method to assemble a non-ledged semiconductor package (1) comprises the following steps. A carrier tape (13) is attached to a metal foil (12). A plurality of leadframes (3) is formed in the metal foil (12), each leadframe (3) comprising a die pad (4) laterally surrounded by a plurality of contact leads (5). A semiconductor die (2), including an active surface with a plurality of die contact pads (7), is attached to each die attach pad (4) and electrically connected to the leadframe (3) by a plurality of bond wires (9) connecting the die contact pads (7) and the lead contact areas (6) of the contact leads (5). A plurality of leadframes (3), each including a wire bonded semiconductor die, are encapsulated with mold material (10). The carrier tape (13) is removed and the non-ledged semiconductor packages (1) separated.